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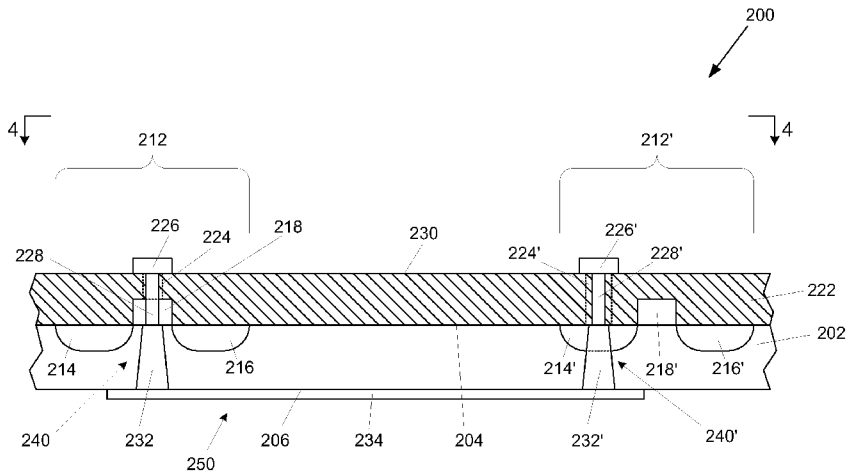


FIG. 3

(57) Abstract: The present description relates to the field of microelectronic devices and the fabrication thereof, wherein through-substrate vias are utilized to route signals between microelectronic integrated circuit components, such as transistors, resistors, capacitors, inductors, and the like, within the microelectronic devices. The through-substrate vias may be used for routing critical signals, which may include, but are not limited to, timing sensitive signal, such as clock signals and the like.

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